

Title (en)
METHOD FOR PRODUCING PLANAR INSULATING LAYERS WITH BREAKTHROUGHS AT THE CORRECT POSITION BY MEANS OF LASER CUTTING AND DEVICES PRODUCED ACCORDINGLY

Title (de)
VERFAHREN ZUR HERSTELLUNG VON PLANAREN ISOLIERSCHICHTEN MIT POSITIONSGERECHTEN DURCHBRÜCHEN MITTELS LASERSCHNEIDEN UND ENTSPRECHEND HERGESTELLTE VORRICHTUNGEN

Title (fr)
PROCÉDÉ POUR PRODUIRE DES COUCHES ISOLANTES PLANES PRÉSENTANT DES OUVERTURES CONFORMES À LA POSITION AU MOYEN D'UNE DÉCOUPE AU LASER ET DISPOSITIFS AINSI PRODUITS

Publication
EP 1987532 A1 20081105 (DE)

Application
EP 06849411 A 20061220

Priority

- EP 2006070021 W 20061220
- DE 102006007795 A 20060220
- DE 102006010523 A 20060307

Abstract (en)
[origin: DE102006010523B3] A method of contacting an electrical contact surface on a substrate (1) and/or a component on this comprises laminating a film of electrically insulating plastic (4) on the surface, making accessible surface contacts (6) through openings (3) formed by laser cutting using a layer of electrically conductive material. The film openings corresponding to the individual contact surfaces are produced according to data determined by automatic optical inspection. An independent claim is also included for a device for the above method.

IPC 8 full level
H01L 21/48 (2006.01); **H01L 21/60** (2006.01); **H01L 23/538** (2006.01); **H01L 23/544** (2006.01)

CPC (source: EP US)
H01L 21/481 (2013.01 - EP US); **H01L 21/486** (2013.01 - EP US); **H01L 23/3164** (2013.01 - EP US); **H01L 23/5389** (2013.01 - EP US); **H01L 23/544** (2013.01 - EP US); **H01L 24/82** (2013.01 - EP US); **H05K 3/281** (2013.01 - EP US); **H01L 2223/5442** (2013.01 - EP US); **H01L 2223/54426** (2013.01 - EP US); **H01L 2223/54473** (2013.01 - EP US); **H01L 2224/2402** (2013.01 - EP US); **H01L 2224/82039** (2013.01 - EP US); **H01L 2224/82047** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/0102** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01057** (2013.01 - EP US); **H01L 2924/01058** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H05K 1/0269** (2013.01 - EP US); **H05K 3/0032** (2013.01 - EP US); **H05K 2201/09918** (2013.01 - EP US); **H05K 2203/063** (2013.01 - EP US); **H05K 2203/166** (2013.01 - EP US); **Y10T 29/49126** (2015.01 - EP US); **Y10T 29/4913** (2015.01 - EP US); **Y10T 29/49155** (2015.01 - EP US); **Y10T 29/49165** (2015.01 - EP US); **Y10T 156/1062** (2015.01 - EP US)

Citation (search report)
See references of WO 2007096017A1

Citation (examination)

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